

ABSTRACTIntegrated circuit singulation method and system

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There is disclosed a method for singulating IC units from a plurality of substrates, the substrates being divided into a sequence of two or more batches in one or more magazines, the method comprising, in a singulation apparatus having a singulation section and a sorting section: sequentially singulating substrates of a first batch in the singulation section and transporting singulated IC units to the sorting section; 10 determining that singulated units of a last substrate of the first batch have reached the sorting section; sequentially processing substrates of a next batch in the sequence until singulated units of the first substrate of the next batch are ready to be sorted in the sorting section; and on receiving an indication that singulated units of the last substrate 15 of the first batch have been cleared from the sorting section, continuing sequential processing of substrates of the next batch.

(Figure 3)